

KYOCERA KE-300TS-1

Epoxy; Epoxide

KYOCERA Chemical Corporation

Message:

High Reliable and Easy-to-Use Molding Compounds for Various Type of Packages

Strong Points

Provide Various Molding Compounds with High Reliability to Cover Many Applications such as LSI, Transistors and Diodes.

Good Curability and Applicable to Various Molding Machines (Both Automated and Conventional)

Low Stress of Large chips and Applicable to Encapsulation.

Application

Smaller SOP, Smaller QFP, DIP, SIP/ZIP, TO-PKG, DPAK, SOT, Unbalanced PKG, Module

General Information		
Uses	Electrical/Electronic Applications	
Physical	Nominal Value	Unit
Specific Gravity	1.80	g/cm ³
Spiral Flow	90.0	cm
Mechanical	Nominal Value	Unit
Flexural Modulus	12500	MPa
Flexural Strength	140	MPa
Thermal	Nominal Value	Unit
Glass Transition Temperature	165	°C
CLTE - Flow		
-- ¹	1.8E-5	cm/cm/°C
-- ²	6.5E-5	cm/cm/°C
Uncured Properties	Nominal Value	Unit
Gel Time	0.50	min
NOTE		
1.	Alpha 1	
2.	Alpha 2	

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